RN00227

Android Automotive Release Notes

Rev. automotive-16.0.0_1.1.0 —
2 March 2026

Release notes

Document information

Information	Content
Keywords	Android, i.MX, Automotive, automotive-16.0.0_1.1.0, RN00227
Abstract	The i.MX Android automotive-16.0.0_1.1.0 release is an Android Automotive GA (RFP) release on NXP's i.MX 8QuadXPlus/8QuadMax MEK and i.MX 95 EVK and Verdin boards and platform.

1 Release Description

The i.MX Android automotive-16.0.0_1.1.0 release is an Android Automotive GA (RFP) release on NXP's i.MX 8QuadMax MEK and i.MX 95 EVK and Verdin boards and platforms. The release is based on Android 16. It supports the device type in-vehicle infotainment defined in https://source.android.com/devices/automotive/.

i.MX Android automotive-16.0.0_1.1.0 release includes all necessary code, documents, and tools to assist users in building and running Android Automotive on the i.MX 8QuadMax MEK board and i.MX 95 EVK/Verdin boards from scratch. Pre-built images are also included for a quick trial on the following platforms:

- i.MX 8QuadMax MEK Board and Platform
- i.MX 95 EVK/Verdin Boards and Platform

This release includes all portings and enhancements based on the Android open source code.

Most of the deliveries in this release are provided in the source code except for some proprietary modules/ libraries from third parties.

2 Supported Hardware SoC/Boards

The supported hardware system-on-chip (SoCs)/boards are listed as follows:

- i.MX 8QuadMax (Silicon Revision B0) MEK Board and Platform.
- i.MX 95 (Silicon Revision B0 19x19) EVK and Verdin Boards and Platforms.

3 Release Package Contents

The `automotive-16.0.0_1.1.0` release package includes the following software and documents.

Table 1. Release package contents

i.MX Android proprietary source code package	• `imx-automotive-16.0.0_1.1.0.tar.gz`: i.MX Android Automotive proprietary source code package to enable Android Automotive on i.MX boards. For example, Hardware Abstraction Layer implementation, and hardware codec acceleration.
Documents	The following documents are included in `android_automotive-16.0.0_1.1.0_docs.zip`: • *Android Automotive Release Notes* (RN00227): A document that introduces key updates and known issues in this release. • *Android Automotive User's Guide* (UG10176): A document describing procedures for configuring and building this release package. • *Android Automotive Quick Start Guide* (UG10177): A document that explains how to run Android Automotive on an i.MX board using prebuilt images. • *i.MX Android Extended Codec Release Notes* (RN00202): A document that provides the extended codec information. • *i.MX Android Security User's Guide* (UG10158): A document that describes how to do customization work on security features supported by i.MX Android software. • *i.MX Graphics User's Guide* (UG10159): A document that describes graphics APIs, Tools, Memory, and Application programming guidelines.
Prebuilt images	You can test Android Automotive with a prebuilt image on the i.MX reference board before building any code: • `automotive-16.0.0_1.1.0_image_8qmek_car.tar.gz`: Prebuilt-image for i.MX 8QuadXPlus/8QuadMax MEK board with the Exterior View System (EVS) function enabled in the ARM Cortex-M4 CPU core during Android OS boot process when the EVS function is switched to the Cortex-A CPU core, which includes NXP extended features.

Table 1. Release package contents*...continued*

	• `automotive-16.0.0_1.1.0_image_8qmek_car2.tar.gz`: Prebuilt-image for i.MX 8QuadMax/8QuadXPlus MEK board with the EVS function enabled in the ARM Cortex-A CPU core only (EVS function is available after starting the Android OS from Cortex-A core), which includes NXP extended features. • `automotive-16.0.0_1.1.0_image_95evk_car.tar.gz`: Prebuilt-image for i.MX 95 EVK board with the the Exterior View System (EVS) function enabled in the ARM Cortex-M7 CPU core during Android OS boot process when the EVS function is switched to the Cortex-A CPU core, which includes NXP extended features. • `automotive-16.0.0_1.1.0_image_95evk_car2.tar.gz`: Prebuilt-image for i.MX 95 EVK/Verdin boards with the EVS function enabled in the Arm Cortex-A CPU core only (EVS function is available after starting Android OS from Cortex-A core), which includes NXP extended features. All prebuilt images are in a separate package. See the *Android Automotive User's Guide* (UG10176) and *Android Automotive Quick Start Guide* (UG10177) to choose the appropriate image.

4 Features

This section describes the features in this package.

Table 2. Features

Feature	i.MX 8QuadXPlus/ 8QuadMax MEK	i.MX 95 EVK/ Verdin	Remarks
Google Android 16 release	Y	Y	Based on the BP2A android-16.0.0_r1 release.
Linux 6.12.38 kernel (merged with the AOSP kernel)	Y	Y	Based on the Linux OS BSP LF6.12.34_2.1.0 release.
Generic Kernel Image (6.12.38)	Y	Y	Based on AOSP android16-6.12-2025-08_r3.
U-Boot	Y	Y	v2025.04.
Trusty OS	Y	Y	-
Graphics-HW	Y	Y	VeriSilicon GC7000L GPU for i.MX 8QuadXPlus, GC7000XSVX GPU for i.MX 8QuadMax with the 6.4.11.p4 driver. Mali-G310 GPU with the r54p1-11eac0 driver for i.MX 95 EVK/Verdin.
Graphics-HW 3D acceleration	Y	Y	OpenGL ES 1.1/2.0/3.1 through GC7000L for i.MX 8QuadXPlus, OpenGL ES 1.1/2.0/3.1/3.2 through GC7000XSVX for i.MX 8QuadMax, Vulkan 1.4 through Mali-G310 for i.MX 95.
Graphics-HW accelerated UI surface composition	Y	Y	OpenGL ES 3.1 through GC7000L for i.MX 8QuadXPlus, OpenGL ES 3.2 through GC7000XSVX for i.MX 8QuadMax, Vulkan 1.4 through Mali-G310 for i.MX 95.
SCFW	Y	N	Version 1.18.0.
SECO firmware	Y	N	Version 3.8.5 for i.MX 8QuadMax B0, i.MX 8QuadXPlus B0, and i.MX 8QuadXPlus C0.
Boot source	eMMC	eMMC	-
Splash Screen	Y	Y	-

Table 2. Features*...continued*

Feature	i.MX 8QuadXPlus/ 8QuadMax MEK	i.MX 95 EVK/ Verdin	Remarks
UI (input)	Y	Y	Supports the USB mouse and Multi-touch over USB.
UI (display)	HDMI display	Y	• Maximum display resolution for i.MX 8QuadMax: Physical HDMI: 3840 x 2160 LVDS-to-HDMI/MIPI-to-HDMI: 1920 x 1080 • Maximum display resolution for i.MX 8QuadXPlus: LVDS-to-HDMI/MIPI-to-HDMI: 1920 x 1080 • Maximum display resolution for i.MX 95: MIPI-to-HDMI: 1920 x 1080 LVDS-to-HDMI: 1920 x 1080
UI (brightness control)	N	N	-
Storage - External Media	Y	Y	-
Connectivity - Ethernet	Y	Y	Atheros AR8031.
Connectivity - Bluetooth wireless technology	Y	Y	PCIE9098 (Murata LBEE5ZZ1XL) for i.MX 8QuadMax and 8QuadXPlus. PCIE9098 (U-Blox JODY-W377) for i.MX 95 EVK. PCIE AW693 for i.MX 95 EVK. PCIE9098 (U-Blox JODY-W271) for i.MX 95 Verdin. Profiles: A2DP Sink, AVRCP, BLE Host, HFP, PBAPClient, MAPMCE, PAN.
Connectivity - Wi-Fi	Y	Y	PCIE9098 (Murata LBEE5ZZ1XL) for i.MX 8QuadMax and 8QuadXPlus. PCIE9098 (U-Blox JODY-W3) for i.MX 95. PCIE AW693 for i.MX 95 EVK. PCIE9098 (U-Blox JODY-W271) for i.MX 95 Verdin. Features: STA mode, AP mode.
Connectivity - USB Tethering	Y	Y	Supports Wi-Fi as upstream.
Power - CPU Freq	Y	Y	-
Power - Bus Freq	Y	Y	-
Media - Music Play	Y	Y	i.MX 8/95: SAI+WM8960 or WM8962. i.MX 8: ESAI+CS42888 (no support for multichannel). i.MX 95: SAI+CS42888 (no support for multichannel).
Media - HDMI audio output	N	N	-
Misc - ADB over USB	Y	Y	-
Misc - Fastboot utility	Y	Y	-
Misc - SW update and factory reset	Y	Y	-
File-based Encryption	Y	Y	-
webGL	Y	Y	-
Vulkan	Y	Y	-
USB TYPEC PD	Y	Y	-
OTA for A/B	Y	Y	-

Table 2. Features*...continued*

Feature	i.MX 8QuadXPlus/ 8QuadMax MEK	i.MX 95 EVK/ Verdin	Remarks
TEE backed Keymaster HAL	Y	Y	This is based on the i.MX Trusty OS TEE firmware.
TEE backed AVB	Y	Y	This is based on the i.MX Trusty OS TEE firmware and secure storage of eMMC chip. In this release, the RPMB part needs to be initialized manually.
Secure boot	Y	Y	Secure boot based on AHAB.
Encrypted boot	Y	Y	-
TEE backed security	Y	Y	This is based on i.MX Trusty OS TEE firmware.
Software backed OEM unlock	Y	Y	Supports software backed OEM lock AIDL and store the `oem unlocking` flag to the `fbmisc` partition.
Virtualization Android	N	N	Supports virtualization Android on i.MX 95 Xen.
EdgeLock Secure Enclave HAL	N	Y	Supports EdgeLock Secure Enclave (ELE) HAL.
Media rearview camera	Y	Y	MAX9286 camera for i.MX 8QuadMax and 8Quad XPlus, MAX96724 with Camera sensors OX03C10 or AP1302 Camera sensor for i.MX 95.
Car Audio Policy	Y	Y	All sounds are played from the audio jack on the CPU board. Rear zone audio is played to an extended audio board (CS42888 codec). Rear zone audio is an optional audio path.

5 Multimedia Codecs

For multimedia codecs and features, see the *i.MX Android Extended Codec Release Notes* (RN00202).

6 Change Logs

Compared to the automotive-15.0.0_2.1.0 release, automotive-16.0.0_1.1.0 has the following major changes:

- Upgraded the Android code base from AP3A android-15.0.0_r32 to BP2A android-16.0.0_r1.
- Upgraded the i.MX kernel from v6.12.23 to v6.12.38.
- Upgraded the GKI kernel from android16-6.12 to android16-6.12-2025-08_r3.
- Supports i.MX 95 B0 19x19 Verdin EVK.
- Wi-Fi/Bluetooth integrated WCS 25Q3 release.
- Upgraded the STS tool to 16_sts-r40. Upgraded the CTS tool to 16_r2. Upgraded the VTS tool to 16_r1 based on the AOSP android-16.0.0_r1 tag.
- Upgraded the Mali GPU driver and WSIALLOC from r54p0 to r54p1.
- Upgraded the VeriSilicon GPU driver from 6.4.11.p3 to 6.4.11.p4.
- Upgraded ISP from 4.2.2_p25.2 to 4.2.2_p25.3.
- Integrated the Trusty OS project into the Android project.
- Upgraded the Thermal HAL to V3.
- Upgraded the Hardware Composer HAL to V4.
- Upgraded the KeyMint HAL to V4.
- Upgraded Widevine CDM from v19.0.1 to v19.5.
- Support of i.MX 8QuadXPlus MEK (Silicon Revision B0, C0) is deprecated and untested.

7 Known Issues and Limitations

The known issues about the hardware and hardware rework instructions are not included in this document. Read all the hardware-related reference materials and ensure that the necessary hardware modifications have been made before using the software.

Table 3. Known issues and limitations

Issue description	Remarks
For i.MX 8QuadXPlus silicon revision B0 chip, it fails to boot from some types of eMMC.	In the default settings, the UUU script burns the boot image into the eMMC Boot Partition with 32 kB offset. Although it works properly on the MEK board, it fails to read the boot image on some types of eMMC. There are two possible solutions: • Download `flash.bin` in the eMMC Boot Partition + 0 kB offset + eMMC fastboot enabled in fuse. • Download `flash.bin` in the eMMC User Partition + 32 kB offset (eMMC fastboot can be either enabled or disabled in fuse). For more information, see https://community.nxp.com/docs/DOC-342877.
The camera may freeze if only one camera is connected to the MAX9286 board.	This issue will be fixed in a future release.
Kernel panic when copying a file through MTP (file transfer mode) with the disabled ADB.	The file is not copied to the target. The copy operation freezes. The issue is caused by “ERR050149: USB3: TRB OUT endpoints transfer blockage and performance delays”.
Boot animation is not available when starting the Car image type.	Boot animation is terminated earlier than starting the `init` process.
EVS functionality degraded on the Car2 image.	Camera output is available after starting the surface flinger.
Changing the HVAC-Auto button value to OFF with the `report` or `echo` command does not work by default after boot.	The Auto button has to be interacted on the HVAC UI at least once. Then, the `report` or `echo` command works. This issue will be fixed in a future release.
For i.MX 95 EVK, the USB-Type C port vbus is connected to a 3.3V power source. Once it is connected to the host and successfully enumerated by the host, the gadget stage is changed to be configured, and the USB HAL acquires its wakelock. Disconnection from the host does not generate a disconnection interrupt. The gadget state keeps unchanged, and the USB HAL does not release its wakelock.	-
For i.MX 8QuadMax, the 9098 Wi-Fi is plugged in the PCIeB slot (base board). The 9098 Wi-Fi firmware loading failed after the Android Automotive OS reboot.	It is a base board design issue. The M.2 slot on the base board does not connect the `#W_DISABLE1` and `#SDIO_WAKE` signals to the i.MX 8 QuadMax chip. The Wi-Fi module 9098 requires to configure these PADs during the boot/start process.
For i.MX 95 EVK Car/Car2 image types, the Gallery application, top bar menu, is not visible (but still works) after interacting with pictures.	The top bar menu can reappear after reconnecting touch or after reopening the application.
For i.MX 8QuadMax, the board stays offline (no ADB or fastboot connection) during reboot stress test. The issue is reproducible after 1000 iterations (around 12 hours).	This issue will be fixed in a future release.

Table 3. Known issues and limitations*...continued*

Issue description	Remarks
For i.MX 95 EVK Car/Car2 image types, the Linux kernel can crash during the reboot of the Android Automotive OS.	The Linux kernel can crash during unmounting the Android file system on the end Android reboot process. This issue will be fixed in a future release.
For i.MX 95 EVK, flashing in serial download mode is not working, i.MX 95 not being detected.	The USB HID device (boot switch configured to serial download mode) cannot be detected on the host PC. This issue occurs on an older board revision: 700-87753 REV X3; SCH-87753 REV A. Workaround: Power off the board by `POWER_SWITCH` (SW4), wait (around 5 seconds) and power on the board by `POWER_SWITCH` again.
Bluetooth volume not working correctly, raising or lowering the volume on the phone does not change the volume of the media file for some types of mobile phones.	This issue will be fixed in a future release.
Pressing forget Wi-Fi sometimes takes longer (around 5-10 seconds) and turns the Wi-Fi switch off (does not cause a Wi-Fi crash). Wi-Fi then has to be manually turned on again.	This issue will be fixed in a future release.
HVAC, `AC temp` temperature range is not taken correctly into account when changing the value from the CMx console (Car image type) or from `/sys/devices/platform/vehicle-dummy/temp_left(right)` (Car2 image type).	This issue will be fixed in a future release.

8 Revision History

This table provides the revision history.

Table 4. Revision history

Document ID	Release date	Description
RN00227 v.automotive-16.0.0_1.1.0	2 March 2026	i.MX 8QuadMax MEK (Silicon Revision B0), i.MX 95 EVK (Silicon 19x19 Revision B0), and i.MX 95 Verdin (Silicon 19x19, Revision B0) GA release
RN00227 v.automotive-15.0.0_2.1.0	14 October 2025	i.MX 8QuadXPlus/8QuadMax MEK (Silicon Revision B0, C0) GA release, i.MX 95 EVK (Silicon 19x19 Revision A1, B0) and i.MX 95 Verdin (Silicon 19x19, Revision A1, B0) Beta
RN00227 v.automotive-15.0.0_1.3.0	21 July 2025	i.MX 8QuadXPlus/8QuadMax MEK (Silicon Revision B0, C0) GA release, i.MX 95 EVK (Silicon Revision A1 19x19) and i.MX 95 Verdin (Silicon Revision A1 19x19) Beta
RN00227 v.automotive-15.0.0_1.1.0	15 May 2025	i.MX 8QuadXPlus/8QuadMax MEK (Silicon Revision B0, C0) GA release, i.MX 95 EVK (Silicon Revision A1 19x19) Beta, and i.MX 95 Verdin (Silicon Revision A1 19x19) Experimental
RN00227 v.automotive-14.0.0_2.3.0	23 January 2025	i.MX 8QuadXPlus/8QuadMax MEK (Silicon Revision B0, C0) GA release, i.MX 95 EVK (Silicon Revision A1 19x19) Beta, and i.MX 95 Verdin (Silicon Revision A1 19x19) Experimental
RN00227 v.automotive-14.0.0_2.1.0	7 November 2024	i.MX 8QuadXPlus/8QuadMax MEK (Silicon Revision B0, C0) GA release, i.MX 95 EVK (Silicon Revision A1 19x19) Alpha (EAR)

Table 4. Revision history*...continued*

Document ID	Release date	Description
AARN_14.0.0_1.1.0	20 June 2024	i.MX 8QuadXPlus/8QuadMax MEK (Silicon Revision B0, C0) GA release
automotive-13.0.0_2.3.0	4 January 2024	i.MX 8QuadXPlus/8QuadMax MEK (Silicon Revision B0, C0) GA release
automotive-13.0.0_2.1.0	10/2023	i.MX 8QuadXPlus/8QuadMax MEK (Silicon Revision B0, C0) GA release
automotive-13.0.0_1.3.0	07/2023	i.MX 8QuadXPlus/8QuadMax MEK (Silicon Revision B0, C0) GA release
automotive-13.0.0_1.1.0	05/2023	i.MX 8QuadXPlus/8QuadMax MEK (Silicon Revision B0, C0) GA release
automotive-12.1.0_1.1.0	12/2022	i.MX 8QuadXPlus/8QuadMax MEK (Silicon Revision B0, C0) GA release
automotive-12.0.0_2.1.0	09/2022	i.MX 8QuadXPlus/8QuadMax MEK (Silicon Revision B0, C0) GA release
automotive-12.0.0_1.1.0	06/2022	i.MX 8QuadXPlus/8QuadMax MEK (Silicon Revision B0, C0) GA release
automotive-11.0.0_2.5.0	03/2022	i.MX 8QuadXPlus/8QuadMax MEK (Silicon Revision B0, C0) GA release
automotive-11.0.0_2.3.0	12/2021	i.MX 8QuadXPlus/8QuadMax MEK (Silicon Revision B0, C0) GA release
automotive-11.0.0_2.1.0	11/2021	Added the examples for i.MX 8QuadXPlus and upgraded the tool version
android-11.0.0_1.1.0-AUTO	01/2021	i.MX 8QuadXPlus/8QuadMax MEK GA release
android-10.0.0_2.4.0	07/2020	i.MX 8QuadMax MEK GA release
android-10.0.0_2.2.0-AUTO	06/2020	i.MX 8QuadXPlus/8QuadMax MEK GA release
automotive-10.0.0_1.1.0	03/2020	i.MX 8QuadXPlus/8QuadMax MEK (Silicon Revision B0) GA release
P9.0.0_2.1.0-AUTO-ga	08/2019	Updated the location of the SCFW porting kit
P9.0.0_2.1.0-AUTO-ga	04/2019	i.MX 8QuadXPlus/8QuadMax Automotive GA release
P9.0.0_1.0.2-AUTO-beta	01/2019	i.MX 8QuadXPlus/8QuadMax Automotive Beta release
P9.0.0_1.0.2-AUTO-alpha	11/2018	i.MX 8QuadXPlus/8QuadMax Automotive Alpha release
O8.1.0_1.1.0_AUTO-beta	05/2018	i.MX 8QuadXPlus/8QuadMax Beta release
O8.1.0_1.1.0_AUTO-EAR	02/2018	Initial release

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